MEDM-MBA0



MEDM-MBA0 is designed with AMD Quad core G-Series SoC solution and Mini Com express type 10 form factor which is specifically designed for customers who need high-level processing and graphics performance with low power consumption in a long product life solution.

FEATURES

- COM Express type 10, basic form factor
- SoC Solution with high performance processor and advanced multimedia and display features
- AMD Radeon[™] HD 10000 graphics
- LPDDR3 SDRAM 4GB memory on board
- 1x Gen3 PCle x8, 3x Gen2 PCle x1

Support Triple display

Form Factor

| Form Factor | COM Express Type 10 Module |
|---------------------|--|
| Power Input Type | Type 10 Pin out with DC Input |
| | |
| General | |
| Processor | - AMD G-Series FP3 APU TDP: - LX-210 (GX-210KL), 2CU, 1GHz, 4.5W |
| BIOS | AMI BIOS, UEFI Architecture One SPI ROM supported for BIOS F/W and BIOS default setting separated Main BIOS chip support H/W write protect jumper or resistor BOM option |
| System Memory | LPDDR3 SDRAM 4GB memory on board Support DDR3-1666 Maximum Speed |
| Storage Device | SATAIII |
| Expansion Interface | -1x PCIe x8 Interface from SoC chip -3x PCIe x1 Interface from SoC chip |
| | |

| I/O Interface | |
|---------------|---------------------------------|
| Audio | High Definition Audio Interface |
| Ethernet | 1x Gigabit LAN |
| USB | - 8x USB 2.0 |
| | - 2x USB 3.0 |
| | |

| Display | | | |
|-------------------|----------------------|--|--|
| Display Interface | - 1x LVDS - 1x DP | | |

| Mechanical& Er | vironmental |
|-------------------|---|
| Dimension | 84 (L) x 55 (W) x 2.0 (Est.) mm |
| Environment | Operating temperature: 0°C ~ 60°C with passive cooling Storage Temperature: -40°C ~ 85°C Operation Humidity: 5% ~ 95%, non-condensing RoHS compliant |
| EMI Certification | CE, FCC Class B |